

Title (en)
ELECTRICAL BOND CONNECTION ARRANGEMENT

Title (de)
ELEKTRISCHE BONDVERBINDUNGSANORDNUNG

Title (fr)
AGENCEMENT ÉLECTRIQUE DE CONNEXION PAR LIAISON

Publication
EP 2277196 A1 20110126 (DE)

Application
EP 09741955 A 20090403

Priority
• EP 2009053987 W 20090403
• DE 102008001671 A 20080509

Abstract (en)
[origin: WO2009135737A1] The invention relates to an electrical bond connection arrangement between a first electrical contact surface and a second electrical contact surface, having at least one first electric conductor, which is bonded onto at least one of the contact surfaces by way of at least one first bond connection. To this end, at least one further second electric conductor (9) is bonded onto the first electric conductor (8) by way of at least one second bond connection (10, 13), the two bond connections (10) being located offset from each other. The invention further relates to a method for producing an electrical bond connection arrangement, which exists between a first electrical contact surface and a second electrical contact surface.

IPC 8 full level
H01L 21/60 (2006.01); **H01L 23/49** (2006.01)

CPC (source: EP US)
H01L 24/34 (2013.01 - US); **H01L 24/37** (2013.01 - US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US);
H01L 24/78 (2013.01 - EP US); **H01L 24/85** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 2224/1147** (2013.01 - EP US);
H01L 2224/37599 (2013.01 - US); **H01L 2224/45014** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US);
H01L 2224/48091 (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/48455** (2013.01 - EP US);
H01L 2224/4846 (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2224/48699** (2013.01 - EP US);
H01L 2224/49111 (2013.01 - EP US); **H01L 2224/49174** (2013.01 - EP US); **H01L 2224/49426** (2013.01 - EP US);
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H01L 2224/85205 (2013.01 - EP US); **H01L 2224/85207** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US);
H01L 2924/01006 (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US);
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Y10S 228/904 (2013.01 - EP US)

C-Set (source: EP US)

EP
1. **H01L 2224/45124 + H01L 2924/00014**
2. **H01L 2224/48091 + H01L 2924/00014**
3. **H01L 2224/49111 + H01L 2224/48472 + H01L 2924/00**
4. **H01L 2224/49111 + H01L 2224/48247 + H01L 2924/00**
5. **H01L 2224/45014 + H01L 2224/45124 + H01L 2924/00**
6. **H01L 2224/48472 + H01L 2224/48247 + H01L 2924/00**
7. **H01L 2224/85205 + H01L 2224/45124 + H01L 2924/00**
8. **H01L 2224/4846 + H01L 2224/48472 + H01L 2924/00**
9. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
10. **H01L 2924/00014 + H01L 2224/45099**
11. **H01L 2224/85203 + H01L 2924/00**
12. **H01L 2924/00014 + H01L 2224/37099**
13. **H01L 2924/00014 + H01L 2224/85399**
14. **H01L 2924/00014 + H01L 2224/05599**
15. **H01L 2924/00014 + H01L 2224/45014 + H01L 2924/206**
US
1. **H01L 2224/45124 + H01L 2924/00014**
2. **H01L 2224/48091 + H01L 2924/00014**
3. **H01L 2224/49111 + H01L 2224/48472 + H01L 2924/00**
4. **H01L 2224/49111 + H01L 2224/48247 + H01L 2924/00**
5. **H01L 2224/45014 + H01L 2224/45124 + H01L 2924/00**
6. **H01L 2224/48472 + H01L 2224/48247 + H01L 2924/00**
7. **H01L 2224/85205 + H01L 2224/45124 + H01L 2924/00**
8. **H01L 2224/4846 + H01L 2224/48472 + H01L 2924/00**
9. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**
10. **H01L 2924/00014 + H01L 2224/45099**
11. **H01L 2224/85203 + H01L 2924/00**
12. **H01L 2924/00014 + H01L 2224/37099**
13. **H01L 2224/37599 + H01L 2924/00014**
14. **H01L 2924/00014 + H01L 2224/85399**
15. **H01L 2924/00014 + H01L 2224/05599**
16. **H01L 2924/00014 + H01L 2224/45014 + H01L 2924/206**

Designated contracting state (EPC)
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AL BA RS

DOCDB simple family (publication)

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